PATENT APPLICATION

Sheet 1 of 1

FORM PTO-1449	ATTY. DOCKET NO.	APPLICATION NO.	CONFIRMATION NO.
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	200308123-5		
	APPLICANT: ATAKOV, et al		
(Use several sheets if necessary)	FILING DATE: 10/8/2003	GROUP: 3729	

REFERENCE DESIGNATION **U.S. PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER	PUBLICATION DATE	NAME	Pages, Columns, Lines Where Relevant Passages or Figures Appear
	1A	5,973,402	10/1999	Shinriki, et al	
	1B	5,889,233	03/1999	Shimeto, et al	
	1C	5,760,476	06/1998	Varker, et al	
	1D	5,745,984	05/1998	Cole, Jr., et al	
	1E	5,666,722	09/1997	Tamm, et al	
	1F	5,663,102	09/1997	Park	
	1G	5,600,884	02/1997	Kondo, et al	
	1H	5,439,731	08/1995	Lietal	
	1I	5,363,550	11/1994	Aitken, et al	
	1J	5,329,695	07/1994	Traskos, et al	
	1K	5,306,872	04/1994	Kordus, et al	

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	PUBLICATION DATE	NAME OF PATENTEE OR APPLICANT	Pages/Columns/Lines Where Relevant Passages/Figures Appear	Check if Translation attached
	1L					
	1M					
	1N					
	1O					
	1P					

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

	1Q	"Electromigration in Thin Aluminum Films on Titanium Nitride", Journal of Applied Physics, Vol. 47, No. 4, April 1976, pp1203-1208
	1R	"An increase of the Electromigration Reliability of Omic Contacts by Enhancing Backflow Effect", Institute of Electrical Engineers (IEEE), 1995, Zhang, W. et al, pp365-370
	1S	"Evidence of the Electromigration Short-Length Effect in Aluminum-Based Metallurgy with Tungsten Diffusion Bariers", Mat. Res. Soc. Symp. Proc., vol309, 1993 Materials Research Society, pp. 141-149

EXAMINER: A. DEXTER TUGBANG
PRIMARY EXAMINER

DATE CONSIDERED: 10/14/05

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EXAMINER INITIAL		DOCUMENT NUMBER	PUBLICATION DATE	NAME	Pages, Columns, Lines Where Relevant Passages or Figures Appear
	1A	4,861,640	08/1998	Gurol	
	1B	4,296,424	10/1981	Shibasaki et a	
	1C				
	1D				
	1E				
	1F				
	1G				
	1H				
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	1K				

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OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, etc.)

	1Q	""Permitted Electromigration of Tungsen-Plug vias in Chain for Test Structure with Short Inter-Plug Distance", T. Aoki, et al, VMIC Conference, June 7-8, 1994 ISMIC
	1R	
	1S	

Examiner: A. DEXTER TUGBANG
PRIMARY EXAMINER

Date considered: 10/14/05